

Release Notes Appendix for Hightec compiler

Release Notes

Product name: Refer to Package* release notes

Release number: 2.0.0

Type of release: Refer to Package* release notes

Release method: via Release Area

AUTOSAR specification: Refer to Package* release notes

Compiler support: HighTec GNU 4.9.4.1

Processor platform: Refer to Package* release notes

Date: 2021-04-09

Previous release number: Refer to Package* release notes

About this document

Scope and purpose

This document, provides information of compiler and compiler options intended to use for 2.0.0 delivery.

Note: **Here Package refers to BASIC/CD/COM-E/ DEMO package.*



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Tool information

1 Tool information

Table 1 Tool information

Tool description	Version details	
Compiler	Version: 4.9.4.1	Build number: Release HDP-v4.9.4.1-11fcedf: 4.9.4 build on 2020-09-01

1.1 Compiler options

Table 2 HighTec compiler options used

Options	Description
Compiler options	-Wall -std=c99 -O2 -mtc162 -meabi -fno-short-enums -ffunction-sections -fdata-sections -fstrict-volatile-bitfields
Assembler options	-Wall -std=c99 -O2 -mtc162 -meabi -fno-short-enums -ffunction-sections -fdata-sections -fstrict-volatile-bitfields
Linker options	-Wl,--mcpu=tc162 -Wl,--gc-sections -nostartfiles -Wl,-n

Note: *Compiler options which influence code generation and are not listed, should be left to the default compiler settings. All the above-listed compiler options are mandatory.*

Attention: *If the compiler options are changed by the user, and if the generated binary output is different than the one generated by the usage of the mandatory compiler options, the functionality and reliability of the drivers cannot be ensured.*

2 Known issues

This chapter describes the prescribed workarounds for all the open issues identified.

Table 3 Known issues

Module	Issue number	Description
No known issues.		

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